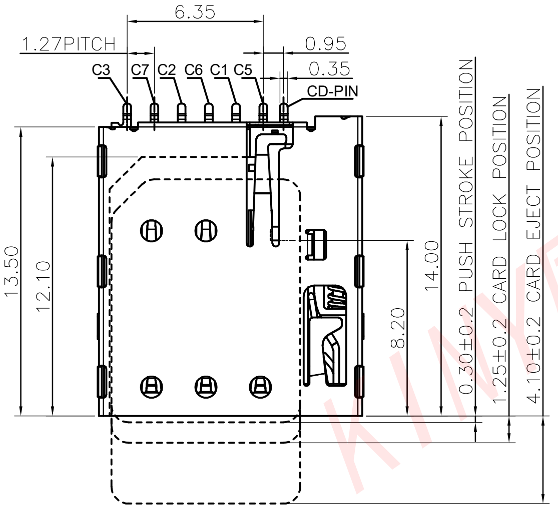
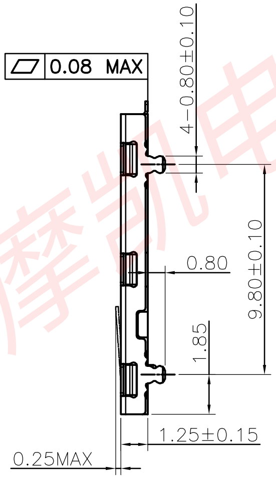
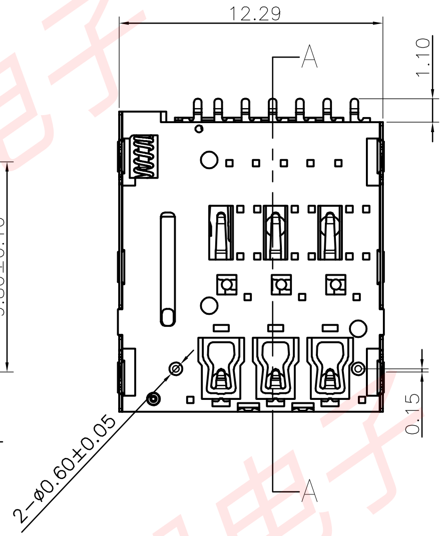
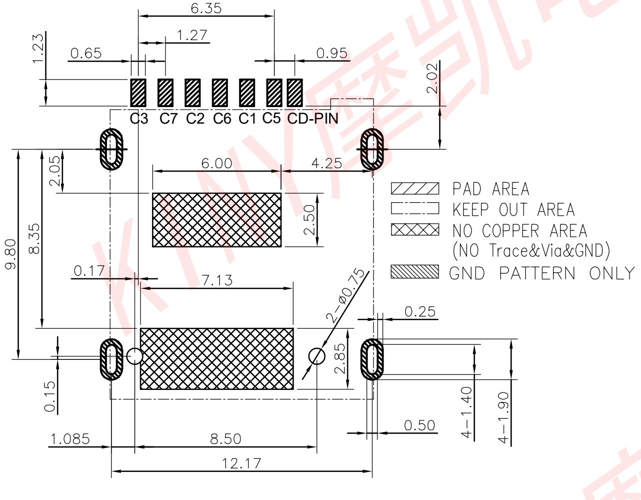
＊ 所有原料材质,生产制程,电镀必须符合HF要求

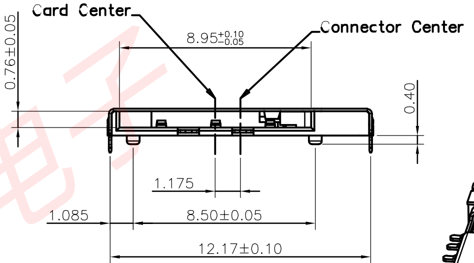


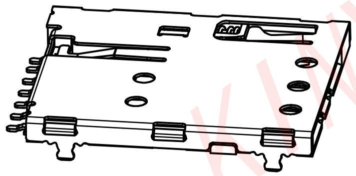


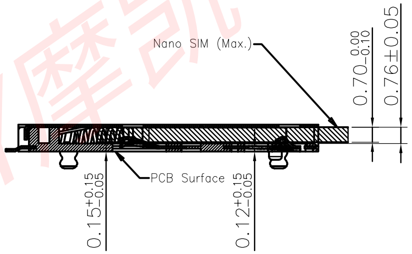




RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



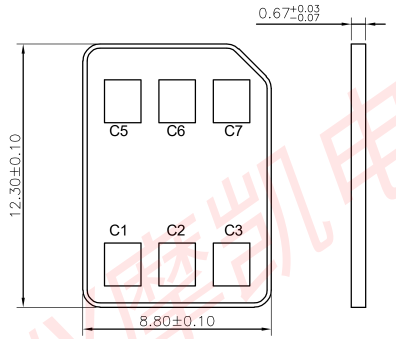




Section A−A

NOTE:

1. Material:
   1−1 Housing:High Temperature Thermoplastic,(LCP S475)Color Black UL 94V−0
   1−2 Contact: Phosphor Bronze(C5210R−H,T=0.12±0.01mm)
   1−3 Cover: SUS304−H T=0.12±0.03mm
2. Plating:
   2−1 Contact terminal:
      Contact area: Gold FLASH.
      Solder area: Sn 120u" Min .
      Underplating: Ni overall 50U" Min.
   2−2 Cover:
      Underplating: Ni overall 50U" Min.
3. Specification:
   3−1.Current Rating :0.5A max.
   3−2.Contact Resistance: 50 mOhms max
   3−3.Insulation Resistance:1000 MOhms min./500VDC
   3−4.Dielectric Withstanding Voltage:500 V AC/1minute
   3−5.Operating Temperature:−25°C to+85°C
   3−6.Mating Cycles:5000 Insertions



COMPOSITION OF DETECTION

CARD DETECT(SW)

GND○—○ ○—○ SW

CARD DETECTION/SWITCH

CARD INSTALLATION: OPEN
NORMAL: SHORT

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
CD	CD/SW
C6	Vpp
C7	I/O

KINY

东莞市摩凯电子有限公司

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
X.X: ±	0.35
X.XX: ±	0.20
X.XXX: ±	0.10
ANGULAR: ±	2°

PRODUCT NAME : NANO SIM H1.25 PUSH/PUSH	DRAWING: Janyz	DATE: 2019.08.23	
PRODUCT NO. : NS125−T1250−01	CHECK: Alex	DATE: 2019.08.23	
DRAWING NO. : D−NS125−T1250−01	APPROVED: Alex	DATE: 2019.08.23	
	SCALE: 1:1	DWG ID: C D	REV.: A	PAGE: 1 OF 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
A	−−−−	NEW RELEASE	Janyz	2019.08.23